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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inter application of:) EXAMINER: DILINH P. NGUYEN
Application No.: 09/880,518) GAU: 2814
Filed: June 12, 2001)
For: BONDING PAD STRUCTURE) ATTORNEY DOCKET: JC-7265-C
Applicant: Kun-Chih Wang) OFFICE ACTION MAILING DATE:
FEB. 19, 2002

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first class mail in an envelope addressed to: Box Non-Fee Amendment, Commissioner for Patents, Washington, D.C. 20231, on May 3, 2002.

Kun-Chih Wang

No fee is believed to be due in connection with this amendment and response to Office Action. If, however, any fee is believed to be due, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account no. 500314.

AMENDMENT AND RESPONSE TO OFFICE ACTION

Box Non Fee Amendment
Commissioner for Patents
Washington, DC 20231

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TECHNOLOGY CENTER 2800

Sir:

In response to the Office Action dated February 19, 2002, please enter the following amendments and consider the following remarks.

IN THE CLAIMS

Please substitute the following clean copy text claims for the pending claims of the number.

*Sub C1
AZ*

1. (Amended) A bonding pad structure, comprising:
a substrate having at least a device section and a non-device section;
a bonding pad layer above the substrate;